



Recent Advances in Intelligent MEMS Sensors

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Message from the Guest Editor

Intelligent MEMS sensors are the product of a fusion between sensor technology and artificial intelligence, and are capable of performing information collection, processing, and storage functions.

This Special Issue aims to provide researchers with a platform for academic exchange in order to conduct in-depth discussions on intelligent MEMS sensors, seek high-quality work, and gain insights into the latest research results, including, but not limited to, the following topics:

- MEMS sensor fault diagnosis and prediction technology;
- MEMS sensor self-calibration method;
- MEMS sensor residual life prediction technology;
- MEMS detection method for abnormal values in sensor signals;
- MEMS self-compensation technology for sensor environmental interference;
- MEMS sensor health management;
- MEMS multi-sensor integration and fusion technology;
- MEMS array sensor signal processing technology;
- New technologies for manufacturing the technology of MEMS sensors;
- New effects and principles of MEMS sensors.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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